

SN74LS175

Quad D Flip-Flop

The LSTTL/MSI SN74LS175 is a high speed Quad D Flip-Flop. The device is useful for general flip-flop requirements where clock and clear inputs are common. The information on the D inputs is stored during the LOW to HIGH clock transition. Both true and complemented outputs of each flip-flop are provided. A Master Reset input resets all flip-flops, independent of the Clock or D inputs, when LOW.

The LS175 is fabricated with the Schottky barrier diode process for high speed and is completely compatible with all ON Semiconductor TTL families.

- Edge-Triggered D-Type Inputs
- Buffered-Positive Edge-Triggered Clock
- Clock to Output Delays of 30 ns
- Asynchronous Common Reset
- True and Complement Output
- Input Clamp Diodes Limit High Speed Termination Effects

GUARANTEED OPERATING RANGES

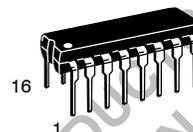
Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
I _{OH}	Output Current - High			-0.4	mA
I _{OL}	Output Current - Low			8.0	mA



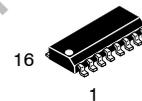
ON Semiconductor™

<http://onsemi.com>

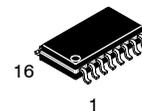
LOW POWER SCHOTTKY



PLASTIC
N SUFFIX
CASE 648



SOIC
D SUFFIX
CASE 751B



SOEIAJ
M SUFFIX
CASE 966

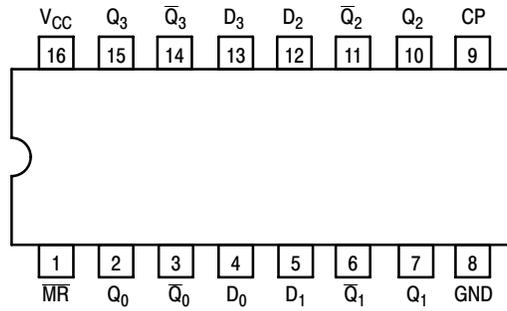
ORDERING INFORMATION

Device	Package	Shipping
SN74LS175N	16 Pin DIP	2000 Units/Box
SN74LS175D	SOIC-16	38 Units/Rail
SN74LS175DR2	SOIC-16	2500/Tape & Reel
SN74LS175M	SOEIAJ-16	See Note 1
SN74LS175MEL	SOEIAJ-16	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

SN74LS175

CONNECTION DIAGRAM DIP (TOP VIEW)



NOTE:
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

PIN NAMES

$D_0 - D_3$	Data Inputs
CP	Clock (Active HIGH Going Edge) Input
\overline{MR}	Master Reset (Active LOW) Input
$Q_0 - Q_3$	True Outputs
$\overline{Q}_0 - \overline{Q}_3$	Complemented Outputs

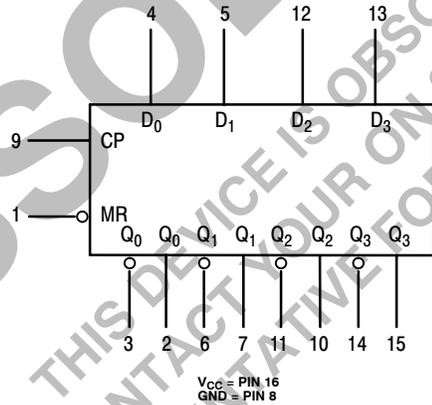
LOADING (Note a)

	HIGH	LOW
$D_0 - D_3$	0.5 U.L.	0.25 U.L.
CP	0.5 U.L.	0.25 U.L.
\overline{MR}	0.5 U.L.	0.25 U.L.
$Q_0 - Q_3$	10 U.L.	5 U.L.
$\overline{Q}_0 - \overline{Q}_3$	10 U.L.	5 U.L.

NOTES:

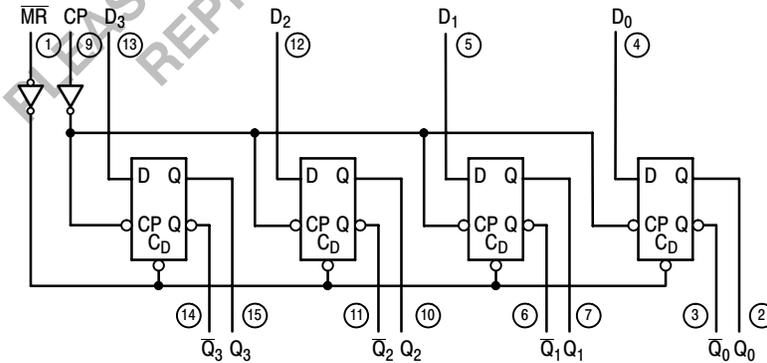
a) 1 TTL Unit Load (U.L.) = 40 μ A HIGH/1.6 mA LOW.

LOGIC SYMBOL



V_{CC} = PIN 16
 GND = PIN 8

LOGIC DIAGRAM



V_{CC} = PIN 16
 GND = PIN 8

○ = PIN NUMBERS

SN74LS175

FUNCTIONAL DESCRIPTION

The LS175 consists of four edge-triggered D flip-flops with individual D inputs and Q and \bar{Q} outputs. The Clock and Master Reset are common. The four flip-flops will store the state of their individual D inputs on the LOW to HIGH Clock (CP) transition, causing individual Q and \bar{Q} outputs to

follow. A LOW input on the Master Reset (\overline{MR}) will force all Q outputs LOW and \bar{Q} outputs HIGH independent of Clock or Data inputs.

The LS175 is useful for general logic applications where a common Master Reset and Clock are acceptable.

TRUTH TABLE

Inputs (t = n, \overline{MR} = H)	Outputs (t = n+1) Note 1	
D	Q	\bar{Q}
L	L	H
H	H	L

Note 1: t = n + 1 indicates conditions after next clock.

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
V _{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	2.7	3.5		V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table
V _{OL}	Output LOW Voltage		0.25	0.4	V	I _{OL} = 4.0 mA
			0.35	0.5	V	I _{OL} = 8.0 mA
I _{IH}	Input HIGH Current			20	μA	V _{CC} = MAX, V _{IN} = 2.7 V
				0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V
I _{IL}	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V
I _{OS}	Short Circuit Current (Note 2)	-20		-100	mA	V _{CC} = MAX
I _{CC}	Power Supply Current			18	mA	V _{CC} = MAX

2. Not more than one output should be shorted at a time, nor for more than 1 second.

SN74LS175

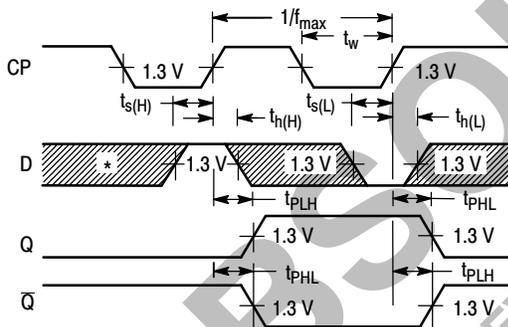
AC CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f _{MAX}	Maximum Input Clock Frequency	30	40		MHz	V _{CC} = 5.0 V C _L = 15 pF
t _{PLH} t _{PHL}	Propagation Delay, \overline{MR} to Output		20 20	30 30	ns	
t _{PLH} t _{PHL}	Propagation Delay, Clock to Output		13 16	25 25	ns	

AC SETUP REQUIREMENTS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
t _W	Clock or \overline{MR} Pulse Width	20			ns	V _{CC} = 5.0 V
t _s	Data Setup Time	20			ns	
t _h	Data Hold Time	5.0			ns	
t _{rec}	Recovery Time	25			ns	

AC WAVEFORMS



*The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock

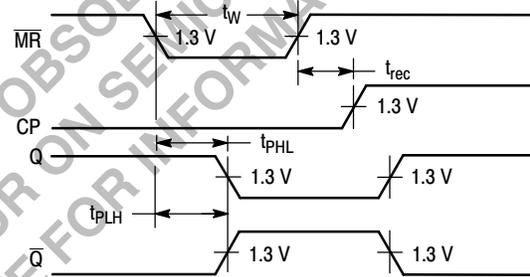


Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

DEFINITIONS OF TERMS

SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW to HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW to HIGH that the logic level must be maintained at the input in order to ensure

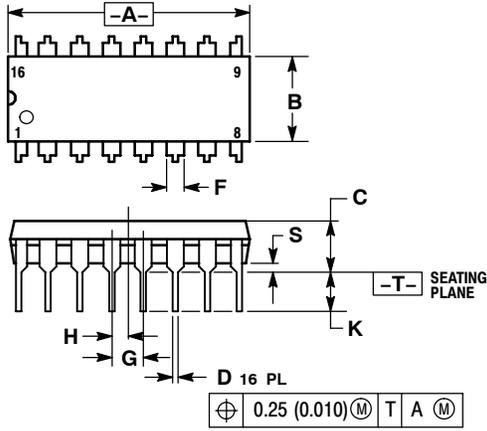
continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW to HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW to HIGH in order to recognize and transfer HIGH Data to the Q outputs.

SN74LS175

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648-08
ISSUE R



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0° 10°		0° 10°	
S	0.020	0.040	0.51	1.01

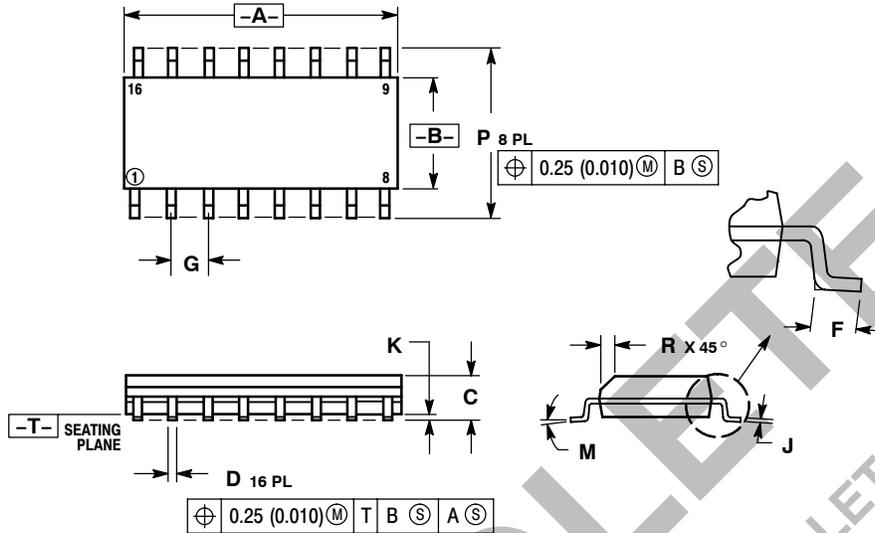
OBSOLETE

THIS DEVICE IS OBSOLETE
 PLEASE CONTACT YOUR ON SEMICONDUCTORS
 REPRESENTATIVE FOR INFORMATION

SN74LS175

PACKAGE DIMENSIONS

D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° 7°		0° 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

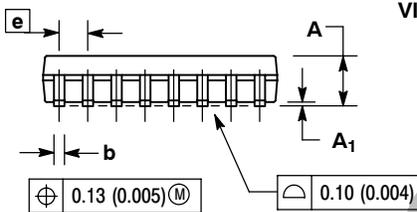
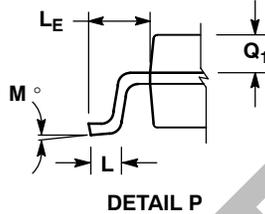
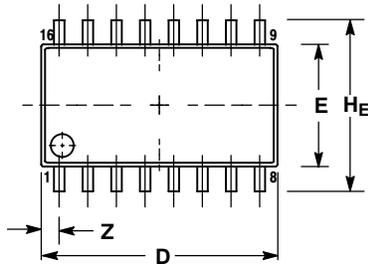
OBSOLETE

THIS DEVICE IS OBSOLETE
PLEASE CONTACT YOUR ON SEMICONDUCTOR
REPRESENTATIVE FOR INFORMATION

SN74LS175

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966-01
ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0° 10°		0° 10°	
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

ON Semiconductor and **ON** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
 Literature Distribution Center for ON Semiconductor
 P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
 Phone: 421 33 790 2910
Japan Customer Focus Center
 Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative